

IN THE SPECIFICATION

Please replace paragraphs [0025], [0029] and [0031] of Applicant's original specification, with the following revised paragraphs:

[0025] During processing, ion bombardment of surfaces exposed to the plasma, such as the upper surface of the substrate, can lead to a substantial heat flux at these surfaces. Therefore, in order to maintain a constant temperature, an equivalent cooling heat flux must be imposed. For example, as shown in FIG. 2, a chuck block 220 underneath the substrate 35 contains a coolant passage ~~25~~ 225 for the transmission of a coolant within the chuck block 220, in order to remove heat from the substrate holder 30, and the substrate 35 via thermal coupling through the micro-gap between the substrate holder 30 and the substrate 35.

[0029] In one embodiment, the apparatus of the present invention comprises: an annular lower metal plenum adapter ring 252 in which the bottom surface is configured to rest on a shelf provided on the substrate holder; and supply and return ports, connected to the lower surface of the adapter ring, for temperature controlled dielectric fluid connections; the ports connecting internal process chamber connections to dielectric fluid supply and return lines.

[0031] Annular nuts 280 and 281 secure a shoulder 290 of the cap to the plenum adapter ring, and a cushioning element such as an o-ring 270 is used with each fastener to protect the cap from point loading damage.